



Material Content Data Sheet



Sales Product Name		BC 817K-25W H6327		Issued		27. September 2017		
MA#		MA000854890						
Package		PG-SOT323-3-1		Weight*		5.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		12	
	noble metal	gold	7440-57-5	0.007	0.12		1184	
	inorganic material	silicon	7440-21-3	0.060	1.01	1.13	10111	11307
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1322	
	non noble metal	copper	7440-50-8	2.617	43.88	44.06	438690	440541
wire	non noble metal	copper	7440-50-8	0.005	0.09	0.09	905	905
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5233	
	plastics	epoxy resin	-	0.671	11.25		112515	
	inorganic material	silicondioxide	60676-86-0	2.419	40.56	52.33	405576	523324
leadfinish	non noble metal	tin	7440-31-5	0.133	2.22	2.22	22245	22245
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1678	1678
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com